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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324j6t6-tr

To obtain the most recent version of this datasheet,
please check at www.st.com>products>technical literature>datasheet.

Please also pay special attention to the Section “KNOWN LIMITATIONS” on page 159.

1 INTRODUCTION

The ST72324 devices are members of the ST7 microcontroller family designed for the 5V operating range.

– The 32-pin devices are designed for mid-range applications

– The 42/44-pin devices target the same range of applications requiring more than 24 I/O ports.

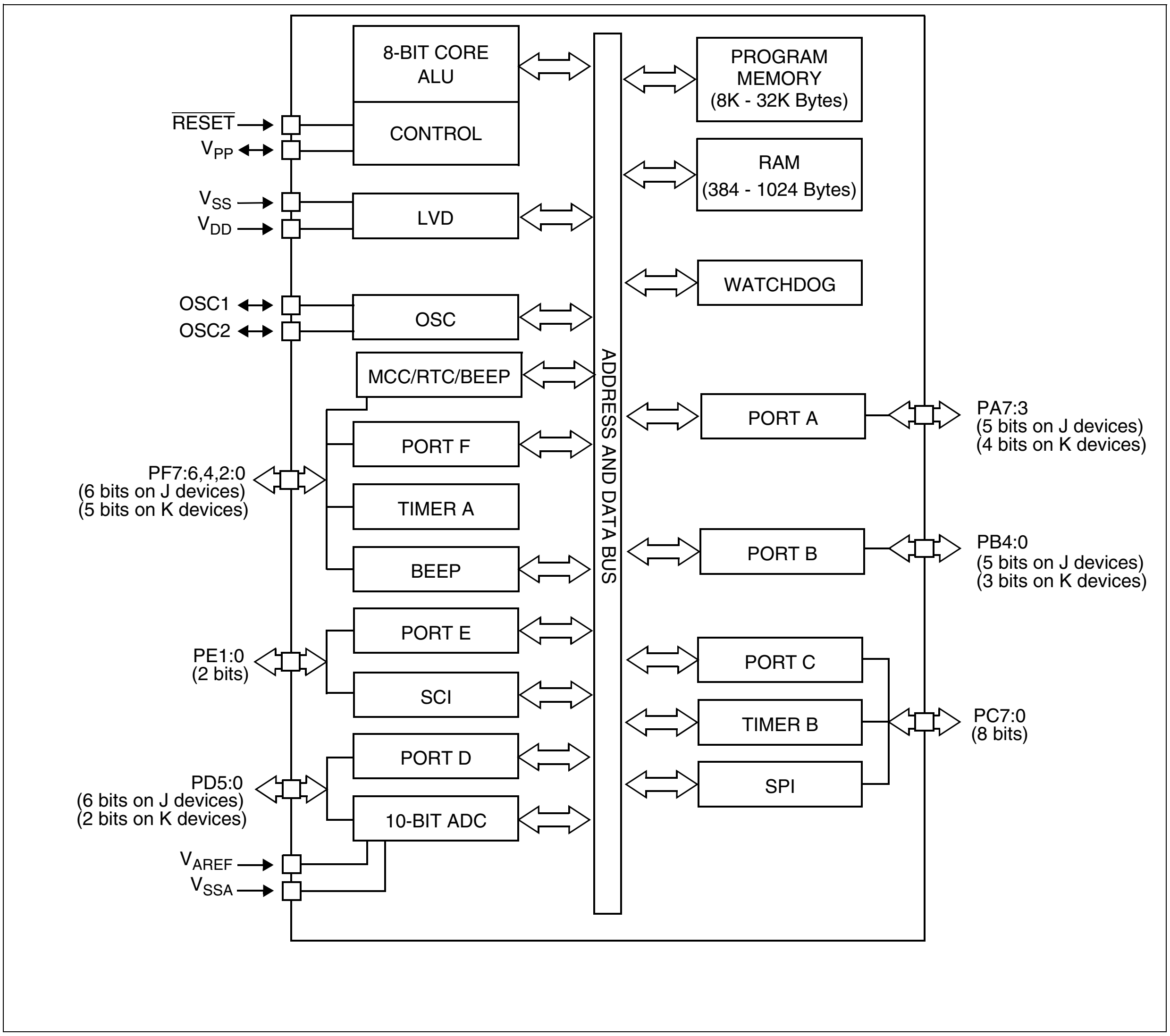
For a description of the differences between ST72324 and ST72324B devices refer to Section 14.2 on page 152

All devices are based on a common industry-standard 8-bit core, featuring an enhanced instruction set and are available with FLASH program memory.

Under software control, all devices can be placed in WAIT, SLOW, ACTIVE-HALT or HALT mode, reducing power consumption when the application is in idle or stand-by state.

The enhanced instruction set and addressing modes of the ST7 offer both power and flexibility to software developers, enabling the design of highly efficient and compact application code. In addition to standard 8-bit data management, all ST7 microcontrollers feature true bit manipulation, 8x8 unsigned multiplication and indirect addressing modes.

Figure 1. Device Block Diagram



PIN DESCRIPTION (Cont'd)

Figure 3. 32-Pin SDIP Package Pinout

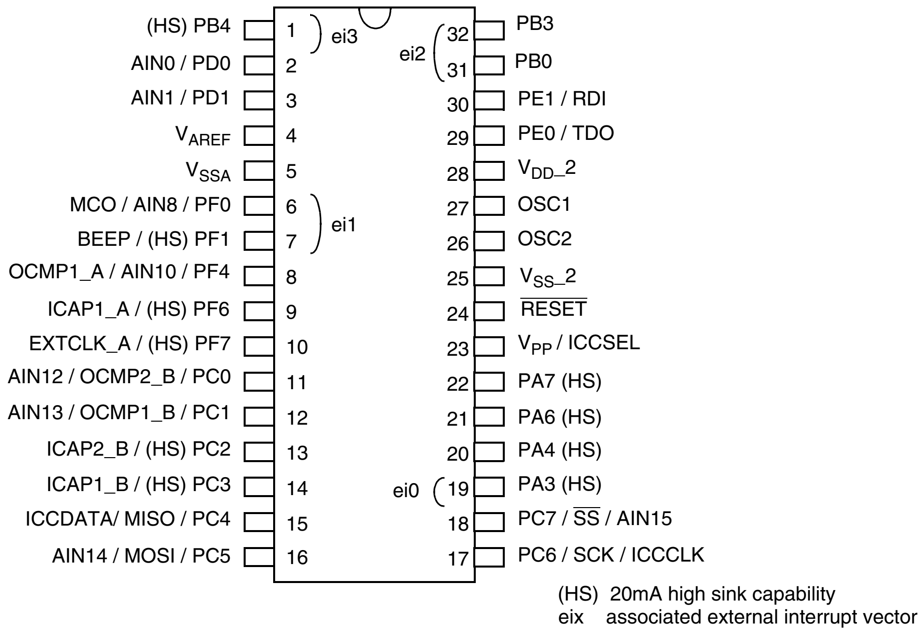
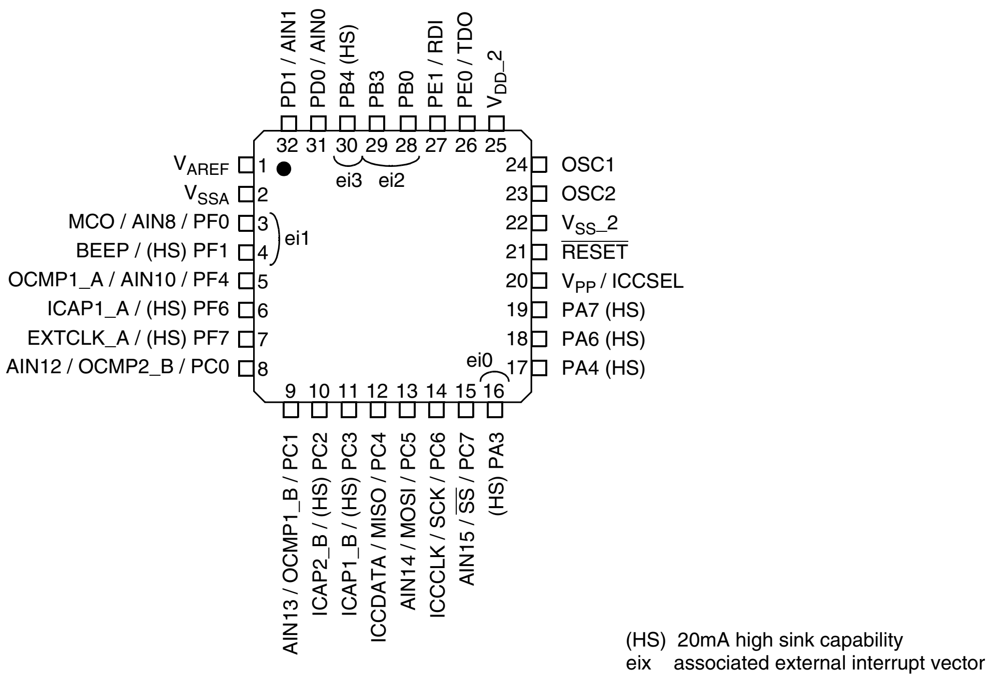


Figure 4. 32-Pin TQFP 7x7 Package Pinout



6.2 MULTI-OSCILLATOR (MO)

The main clock of the ST7 can be generated by three different source types coming from the multi-oscillator block:

- an external source
- 4 crystal or ceramic resonator oscillators
- an internal high frequency RC oscillator

Each oscillator is optimized for a given frequency range in terms of consumption and is selectable through the option byte. The associated hardware configurations are shown in Table 5. Refer to the electrical characteristics section for more details.

Caution: The OSC1 and/or OSC2 pins must not be left unconnected. For the purposes of Failure Mode and Effect Analysis, it should be noted that if the OSC1 and/or OSC2 pins are left unconnected, the ST7 main oscillator may start and, in this configuration, could generate an f_{OSC} clock frequency in excess of the allowed maximum (>16MHz.), putting the ST7 in an unsafe/undefined state. The product behaviour must therefore be considered undefined when the OSC pins are left unconnected.

External Clock Source

In this external clock mode, a clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC1 pin while the OSC2 pin is tied to ground.

Crystal/Ceramic Oscillators

This family of oscillators has the advantage of producing a very accurate rate on the main clock of the ST7. The selection within a list of 4 oscillators with different frequency ranges has to be done by option byte in order to reduce consumption (refer to Section 14.1 on page 150 for more details on the frequency ranges). In this mode of the multi-oscillator, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. The loading capacitance values must be adjusted according to the selected oscillator.

These oscillators are not stopped during the RESET phase to avoid losing time in the oscillator start-up phase.

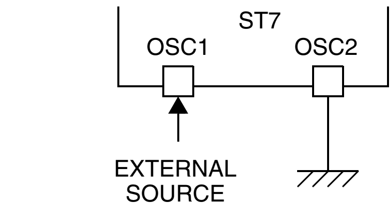
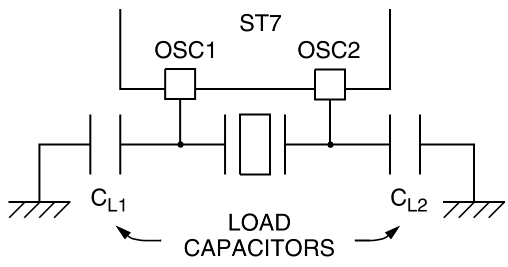
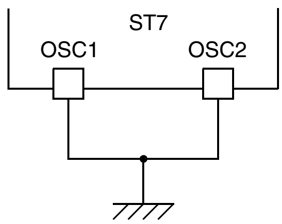
Internal RC Oscillator

This oscillator allows a low cost solution for the main clock of the ST7 using only an internal resistor and capacitor. Internal RC oscillator mode has the drawback of a lower frequency accuracy and should not be used in applications that require accurate timing.

In this mode, the two oscillator pins have to be tied to ground.

In order not to exceed the max. operating frequency, the internal RC oscillator must not be used with the PLL.

Table 5. ST7 Clock Sources

	Hardware Configuration
External Clock	
Crystal/Ceramic Resonators	
Internal RC Oscillator	

SYSTEM INTEGRITY MANAGEMENT (Cont'd)

6.4.3 Low Power Modes

Mode	Description
WAIT	No effect on SI. AVD interrupt causes the device to exit from Wait mode.
HALT	The CRSR register is frozen.

6.4.3.1 Interrupts

The AVD interrupt event generates an interrupt if the AVDIE bit is set and the interrupt mask in the CC register is reset (RIM instruction).

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
AVD event	AVDF	AVDIE	Yes	No

INTERRUPTS (Cont'd)

7.3 INTERRUPTS AND LOW POWER MODES

All interrupts allow the processor to exit the WAIT low power mode. On the contrary, only external and other specified interrupts allow the processor to exit from the HALT modes (see column "Exit from HALT" in "Interrupt Mapping" table). When several pending interrupts are present while exiting HALT mode, the first one serviced can only be an interrupt with exit from HALT mode capability and it is selected through the same decision process shown in Figure 18.

Note: If an interrupt, that is not able to Exit from HALT mode, is pending with the highest priority when exiting HALT mode, this interrupt is serviced after the first one serviced.

7.4 CONCURRENT & NESTED MANAGEMENT

The following Figure 19 and Figure 20 show two different interrupt management modes. The first is called concurrent mode and does not allow an interrupt to be interrupted, unlike the nested mode in Figure 20. The interrupt hardware priority is given in this order from the lowest to the highest: MAIN, IT4, IT3, IT2, IT1, IT0. The software priority is given for each interrupt.

Warning: A stack overflow may occur without notifying the software of the failure.

Figure 19. Concurrent Interrupt Management

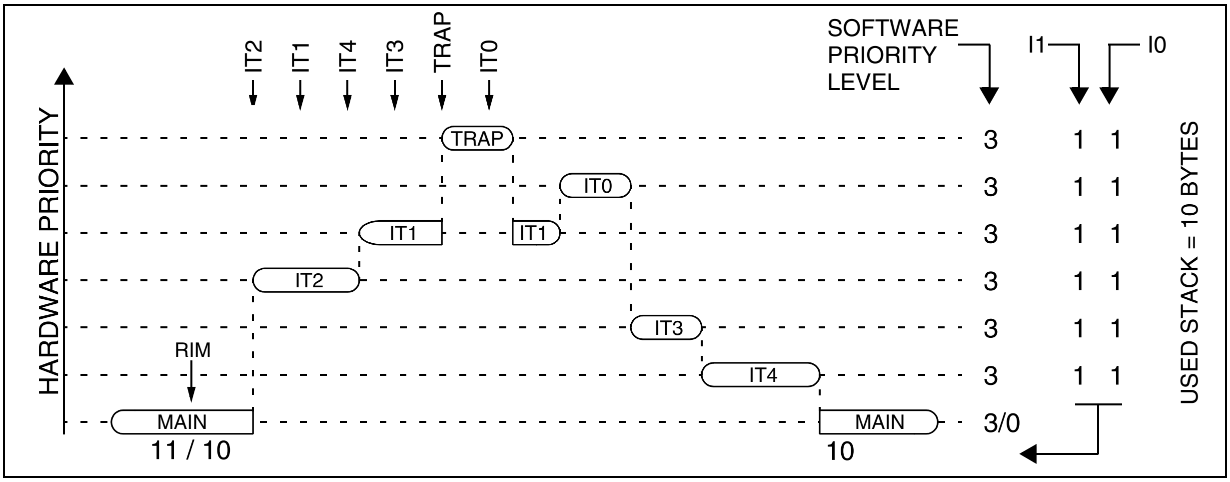


Figure 20. Nested Interrupt Management

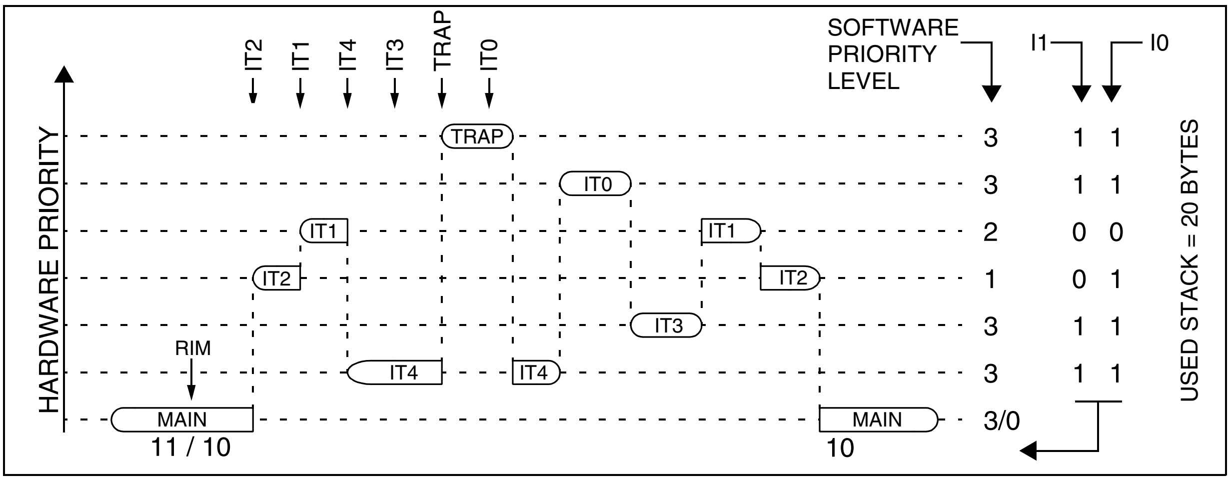
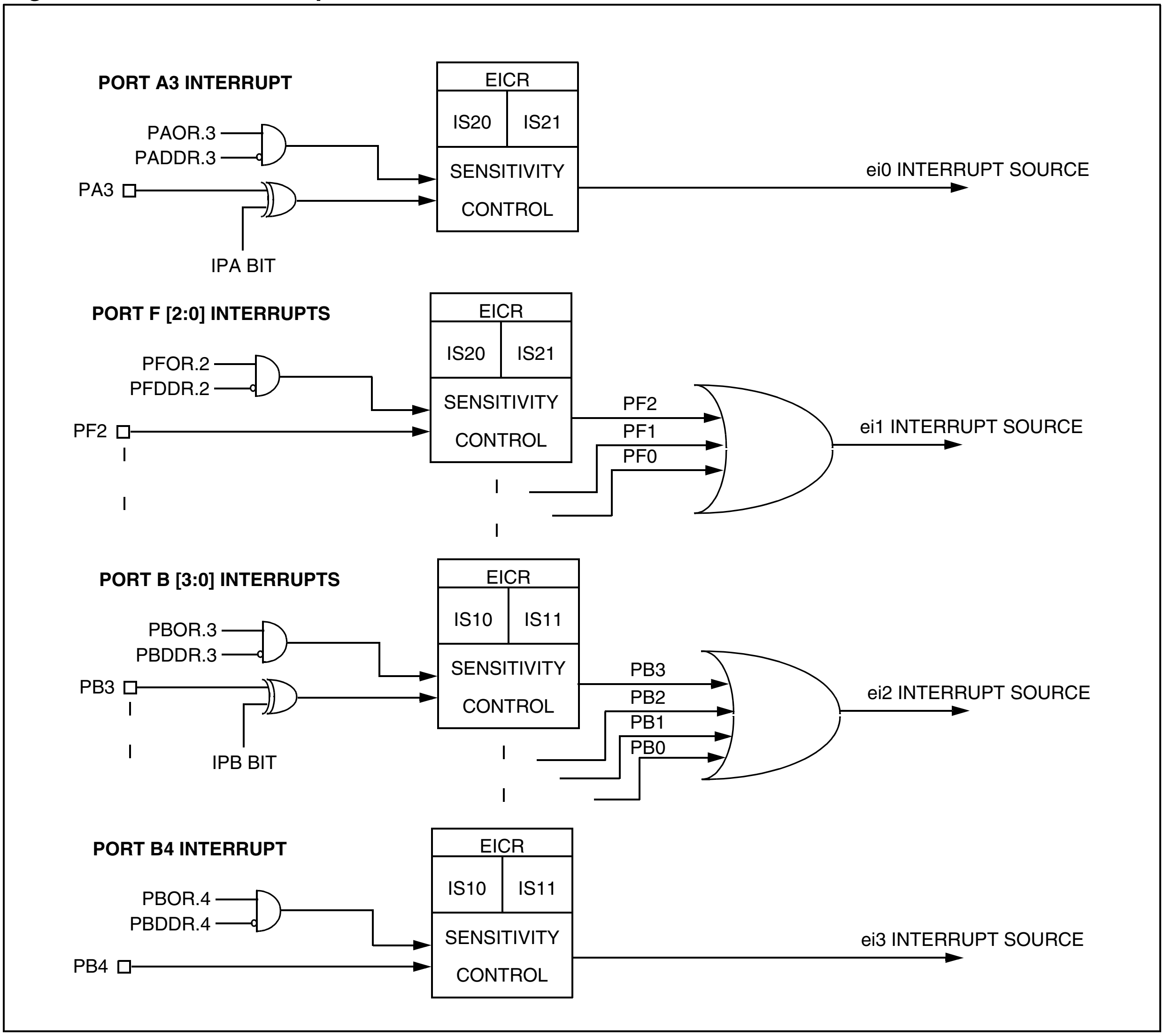


Figure 21. External Interrupt Control bits



I/O PORTS (Cont'd)

Table 13. I/O Port Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
Reset Value of all I/O port registers		0	0	0	0	0	0	0	0
0000h	**PADR**	MSB							LSB
0001h	**PADDR**								
0002h	**PAOR**								
0003h	**PBDR**	MSB							LSB
0004h	**PBDDR**								
0005h	**PBOR**								
0006h	**PCDR**	MSB							LSB
0007h	**PCDDR**								
0008h	**PCOR**								
0009h	**PDDR**	MSB							LSB
000Ah	**PDDDR**								
000Bh	**PDOR**								
000Ch	**PEDR**	MSB							LSB
000Dh	**PEDDR**								
000Eh	**PEOR**								
000Fh	**PFDR**	MSB							LSB
0010h	**PFDDR**								
0011h	**PFOR**								

16-BIT TIMER (Cont'd)

Figure 36. Counter Timing Diagram, internal clock divided by 2

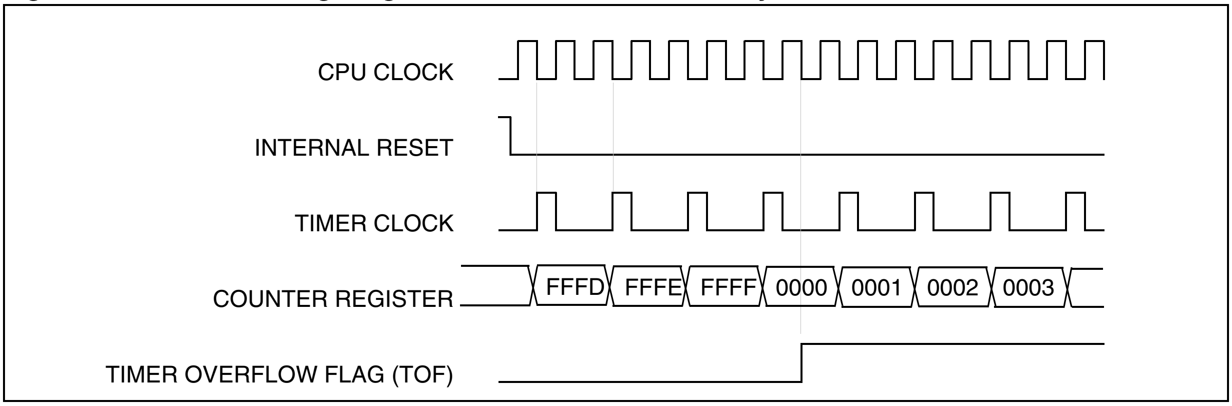


Figure 37. Counter Timing Diagram, internal clock divided by 4

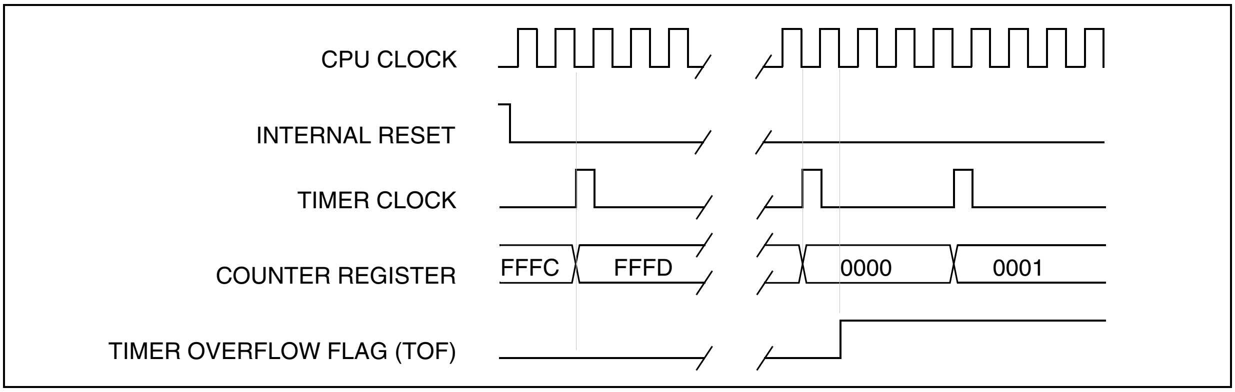
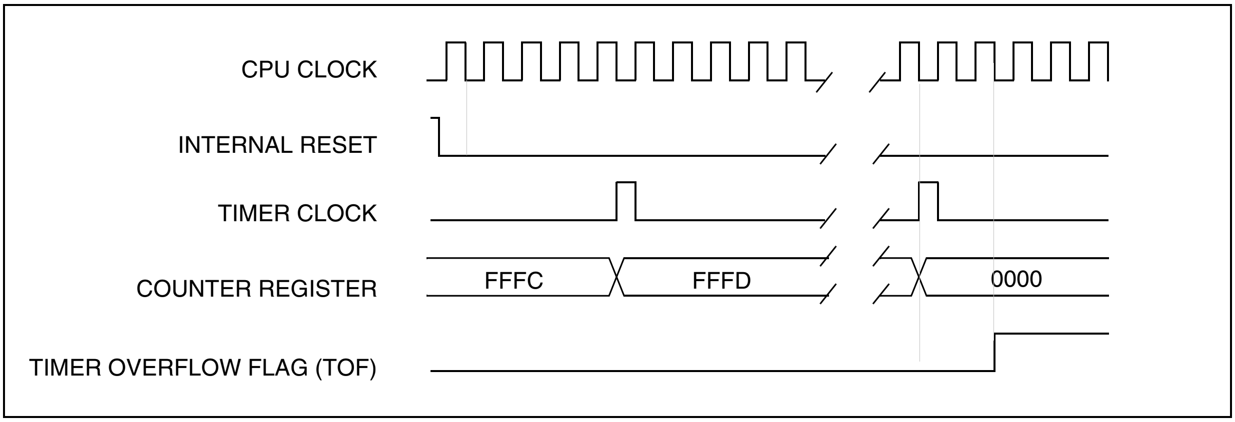


Figure 38. Counter Timing Diagram, internal clock divided by 8



Note: The MCU is in reset state when the internal reset signal is high, when it is low the MCU is running.

16-BIT TIMER (Cont'd)

CONTROL/STATUS REGISTER (CSR)

Read Only (except bit 2 R/W)

Reset Value: xxxx x0xx (xxh)

7							0
ICF1	OCF1	TOF	ICF2	OCF2	TIMD	0	0

Bit 7 = **ICF1** *Input Capture Flag 1.*
0: No input capture (reset value).
1: An input capture has occurred on the ICAP1 pin or the counter has reached the OC2R value in PWM mode. To clear this bit, first read the SR register, then read or write the low byte of the IC1R (IC1LR) register.

Bit 6 = **OCF1** *Output Compare Flag 1.*
0: No match (reset value).
1: The content of the free running counter has matched the content of the OC1R register. To clear this bit, first read the SR register, then read or write the low byte of the OC1R (OC1LR) register.

Bit 5 = **TOF** *Timer Overflow Flag.*
0: No timer overflow (reset value).
1: The free running counter rolled over from FFFFh to 0000h. To clear this bit, first read the SR register, then read or write the low byte of the CR (CLR) register.

Note: Reading or writing the ACLR register does not clear TOF.

Bit 4 = **ICF2** *Input Capture Flag 2.*
0: No input capture (reset value).
1: An input capture has occurred on the ICAP2 pin. To clear this bit, first read the SR register, then read or write the low byte of the IC2R (IC2LR) register.

Note: In Flash devices, this bit is not available for Timer A and is forced by hardware to 0.

Bit 3 = **OCF2** *Output Compare Flag 2.*
0: No match (reset value).
1: The content of the free running counter has matched the content of the OC2R register. To clear this bit, first read the SR register, then read or write the low byte of the OC2R (OC2LR) register.

Note: In Flash devices, this bit is not available for Timer A and is forced by hardware to 0.

Bit 2 = **TIMD** *Timer disable.*
This bit is set and cleared by software. When set, it freezes the timer prescaler and counter and disabled the output functions (OCMP1 and OCMP2 pins) to reduce power consumption. Access to the timer registers is still available, allowing the timer configuration to be changed, or the counter reset, while it is disabled.
0: Timer enabled
1: Timer prescaler, counter and outputs disabled

Bits 1:0 = Reserved, must be kept cleared.

16-BIT TIMER (Cont'd)

INPUT CAPTURE 1 HIGH REGISTER (IC1HR)

Read Only
Reset Value: Undefined

This is an 8-bit read only register that contains the high part of the counter value (transferred by the input capture 1 event).

7							0
MSB							LSB

OUTPUT COMPARE 1 HIGH REGISTER (OC1HR)

Read/Write
Reset Value: 1000 0000 (80h)

This is an 8-bit register that contains the high part of the value to be compared to the CHR register.

7							0
MSB							LSB

INPUT CAPTURE 1 LOW REGISTER (IC1LR)

Read Only
Reset Value: Undefined

This is an 8-bit read only register that contains the low part of the counter value (transferred by the input capture 1 event).

7							0
MSB							LSB

OUTPUT COMPARE 1 LOW REGISTER (OC1LR)

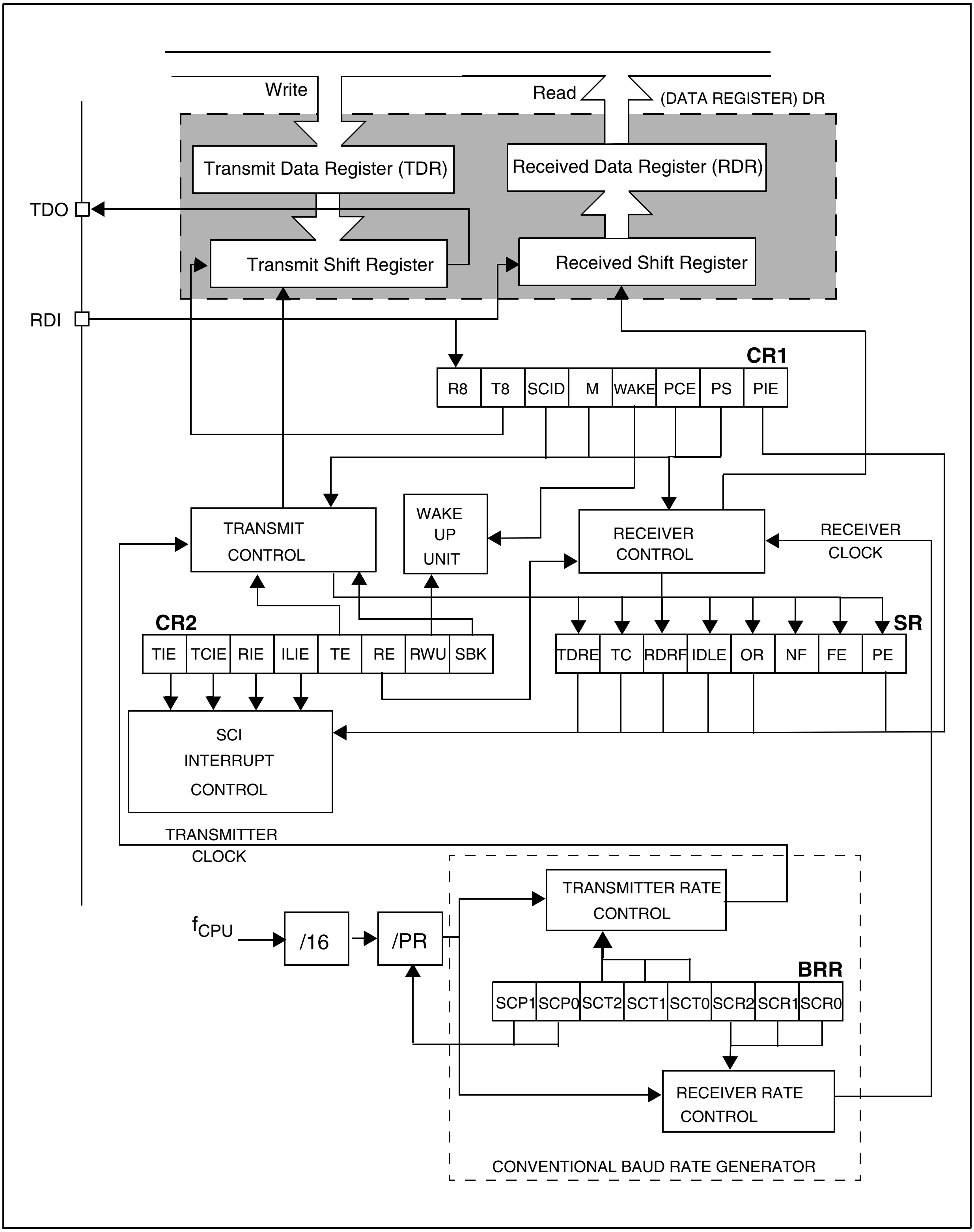
Read/Write
Reset Value: 0000 0000 (00h)

This is an 8-bit register that contains the low part of the value to be compared to the CLR register.

7							0
MSB							LSB

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

Figure 53. SCI Block Diagram



SERIAL COMMUNICATIONS INTERFACE (Cont'd)

CONTROL REGISTER 2 (SCICR2)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK

Bit 7 = **TIE** *Transmitter interrupt enable*.
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever TDRE=1 in the SCISR register

Bit 6 = TCIE *Transmission complete interrupt enable*
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever TC=1 in the SCISR register

Bit 5 = **RIE** *Receiver interrupt enable*.
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever OR=1 or RDRF=1 in the SCISR register

Bit 4 = **ILIE** *Idle line interrupt enable.*
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever IDLE=1 in the SCISR register.

Bit 3 = **TE** *Transmitter enable.*
This bit enables the transmitter. It is set and cleared by software.
0: Transmitter is disabled
1: Transmitter is enabled

Notes:

– During transmission, a “0” pulse on the TE bit (“0” followed by “1”) sends a preamble (idle line) after the current word.

– When TE is set there is a 1 bit-time delay before the transmission starts.

CAUTION: The TDO pin is free for general purpose I/O only when the TE and RE bits are both cleared (or if TE is never set).

Bit 2 = **RE** *Receiver enable.*
This bit enables the receiver. It is set and cleared by software.
0: Receiver is disabled
1: Receiver is enabled and begins searching for a start bit

Bit 1 = **RWU** *Receiver wake-up.*
This bit determines if the SCI is in mute mode or not. It is set and cleared by software and can be cleared by hardware when a wake-up sequence is recognized.
0: Receiver in Active mode
1: Receiver in Mute mode

Note: Before selecting Mute mode (setting the RWU bit), the SCI must receive some data first, otherwise it cannot function in Mute mode with wake-up by idle line detection.

Bit 0 = **SBK** *Send break.*
This bit set is used to send break characters. It is set and cleared by software.
0: No break character is transmitted
1: Break characters are transmitted

Note: If the SBK bit is set to “1” and then to “0”, the transmitter sends a BREAK word at the end of the current word.

10.6 10-BIT A/D CONVERTER (ADC)

10.6.1 Introduction

The on-chip Analog to Digital Converter (ADC) peripheral is a 10-bit, successive approximation converter with internal sample and hold circuitry. This peripheral has up to 16 multiplexed analog input channels (refer to device pin out description) that allow the peripheral to convert the analog voltage levels from up to 16 different sources.

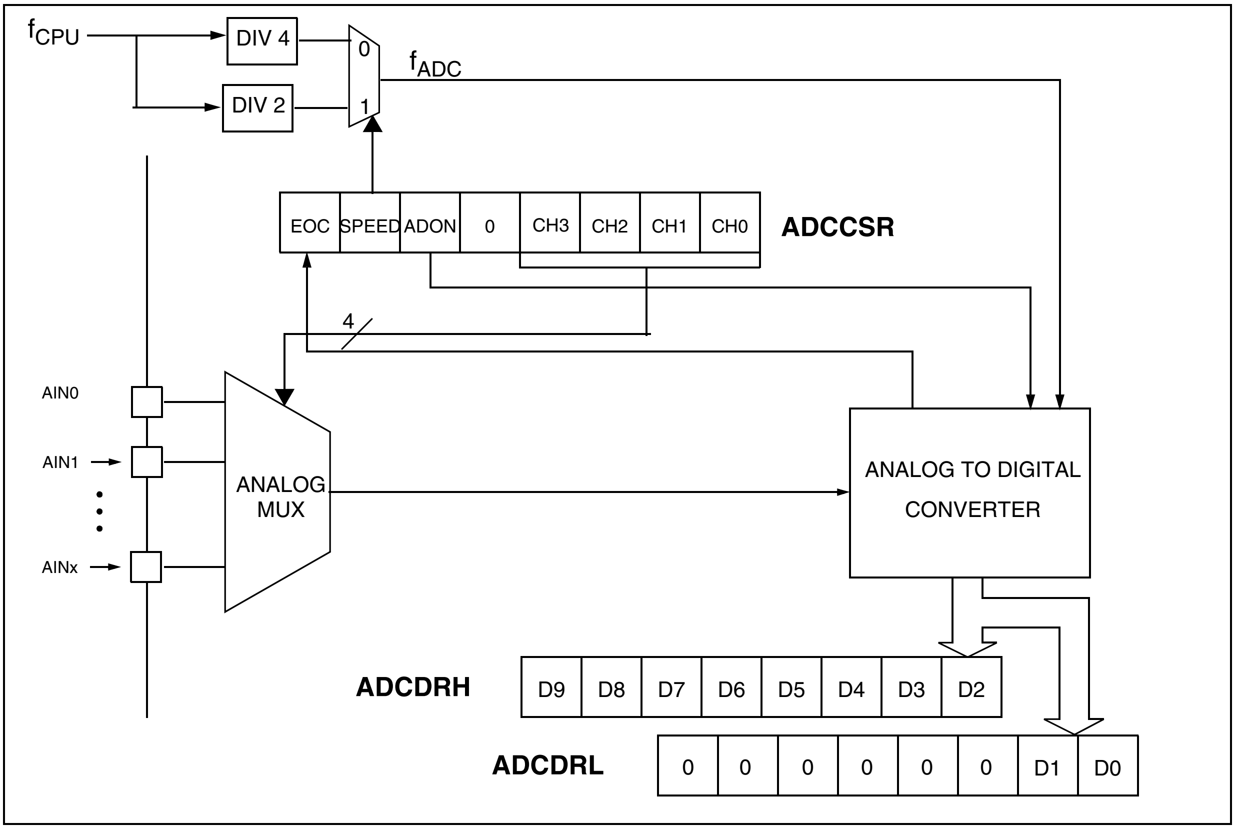
The result of the conversion is stored in a 10-bit Data Register. The A/D converter is controlled through a Control/Status Register.

10.6.2 Main Features

- 10-bit conversion
- Up to 16 channels with multiplexed input
- Linear successive approximation
- Data register (DR) which contains the results
- Conversion complete status flag
- On/off bit (to reduce consumption)

The block diagram is shown in Figure 57.

Figure 57. ADC Block Diagram



INSTRUCTION SET OVERVIEW (Cont'd)

Mnemo	Description	Function/Example	Dst	Src	I1	H	I0	N	Z	C
JRULE	Jump if (C + Z = 1)	Unsigned <=								
LD	Load	dst <= src	reg, M	M, reg				N	Z	
MUL	Multiply	X,A = X * A	A, X, Y	X, Y, A		0				0
NEG	Negate (2's compl)	neg $10	reg, M					N	Z	C
NOP	No Operation									
OR	OR operation	A = A + M	A	M				N	Z	
POP	Pop from the Stack	pop reg	reg	M						
		pop CC	CC	M	I1	H	I0	N	Z	C
PUSH	Push onto the Stack	push Y	M	reg, CC						
RCF	Reset carry flag	C = 0								0
RET	Subroutine Return									
RIM	Enable Interrupts	I1:0 = 10 (level 0)			1		0			
RLC	Rotate left true C	C <= A <= C	reg, M					N	Z	C
RRC	Rotate right true C	C => A => C	reg, M					N	Z	C
RSP	Reset Stack Pointer	S = Max allowed								
SBC	Substract with Carry	A = A - M - C	A	M				N	Z	C
SCF	Set carry flag	C = 1								1
SIM	Disable Interrupts	I1:0 = 11 (level 3)			1		1			
SLA	Shift left Arithmetic	C <= A <= 0	reg, M					N	Z	C
SLL	Shift left Logic	C <= A <= 0	reg, M					N	Z	C
SRL	Shift right Logic	0 => A => C	reg, M					0	Z	C
SRA	Shift right Arithmetic	A7 => A => C	reg, M					N	Z	C
SUB	Substraction	A = A - M	A	M				N	Z	C
SWAP	SWAP nibbles	A7-A4 <=> A3-A0	reg, M					N	Z	
TNZ	Test for Neg & Zero	tnz lbl1						N	Z	
TRAP	S/W trap	S/W interrupt			1		1			
WFI	Wait for Interrupt				1		0			
XOR	Exclusive OR	A = A XOR M	A	M				N	Z	

SUPPLY CURRENT CHARACTERISTICS (Cont'd)

12.5.2 Supply and Clock Managers

The previous current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To get the total device consumption, the two current values must be added (except for HALT mode).

Symbol	Parameter	Conditions	Typ	Max	Unit
$I_{DD(RCINT)}$	Supply current of internal RC oscillator		625		μA
$I_{DD(RES)}$	Supply current of resonator oscillator [1) & 2)]		see Section 12.6.3 on page 125		
$I_{DD(PLL)}$	PLL supply current	V_{DD}= 5V	360		μA
$I_{DD(LVD)}$	LVD supply current	V_{DD}= 5V	150	300	

Notes:

1. Data based on characterization results done with the external components specified in Section 12.6.3, not tested in production.
2. As the oscillator is based on a current source, the consumption does not depend on the voltage.

EMC CHARACTERISTICS (Cont'd)

12.8.2 Electro Magnetic Interference (EMI)

Based on a simple application running on the product (toggling 2 LEDs through the I/O ports), the product is monitored in terms of emission. This emission test is in line with the norm SAE J 1752/3 which specifies the board and the loading of each pin.

Symbol	Parameter	Conditions	Device/ Package	Monitored Frequency Band	Max vs. [f_{OSC}/f_{CPU}]		Unit
					8/4MHz	16/8MHz	
S_{EMI}	Peak level	V_{DD}=5V, T_A=+25°C conforming to SAE J 1752/3	8/16K Flash/ TQFP44	0.1MHz to 30MHz	12	18	dBµV
				30MHz to 130MHz	19	25	
				130MHz to 1GHz	15	22	
				SAE EMI Level	3	3.5	-
			32K Flash/TQFP44	0.1MHz to 30MHz	20	21	dBµV
				30MHz to 130MHz	26	31	
				130MHz to 1GHz	22	28	
				SAE EMI Level	3.5	4.0	-
			Flash/TQFP32	0.1MHz to 30MHz	25	27	dBµV
				30MHz to 130MHz	30	36	
				130MHz to 1GHz	18	23	
				SAE EMI Level	3.0	3.5	-

Notes:
1. Data based on characterization results, not tested in production.
2. Refer to Application Note AN1709 for data on other package types.

I/O PORT PIN CHARACTERISTICS (Cont'd)

12.9.2 Output Driving Current

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A unless otherwise specified.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{OL} 1)	Output low level voltage for a standard I/O pin when 8 pins are sunk at same time (see Figure 71)	V_{DD}=5V	I_{IO}=+5mA		1.2	V
			I_{IO}=+2mA		0.5	
	Output low level voltage for a high sink I/O pin when 4 pins are sunk at same time (see Figure 72 and Figure 74)		I_{IO}=+20mA, $T_A \leq 85°C$ $T_A > 85°C$		1.3 1.5	
			I_{IO}=+8mA		0.6	
V_{OH} 2)	Output high level voltage for an I/O pin when 4 pins are sourced at same time (see Figure 73 and Figure 76)		I_{IO}=-5mA, $T_A \leq 85°C$ $T_A > 85°C$	V_{DD}-1.4 V_{DD}-1.6		
			I_{IO}=-2mA	V_{DD}-0.7		

Figure 71. Typical V_{OL} at V_{DD}=5V (std. ports)

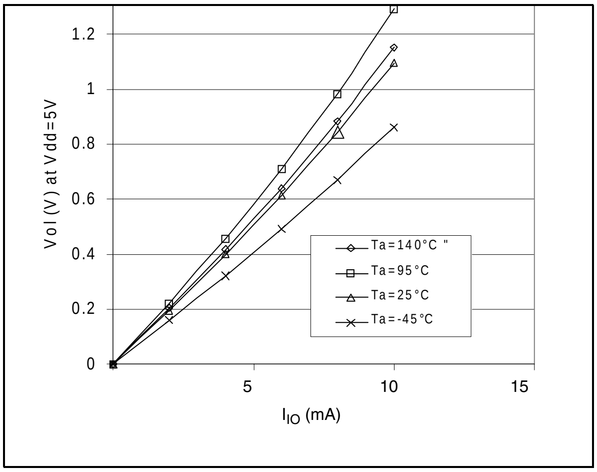


Figure 73. Typical V_{OH} at V_{DD}=5V

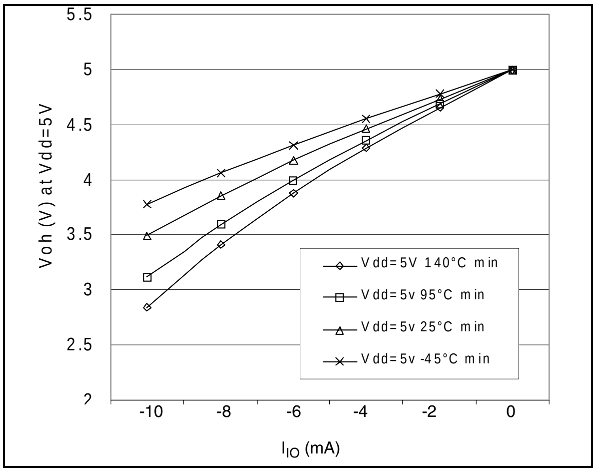
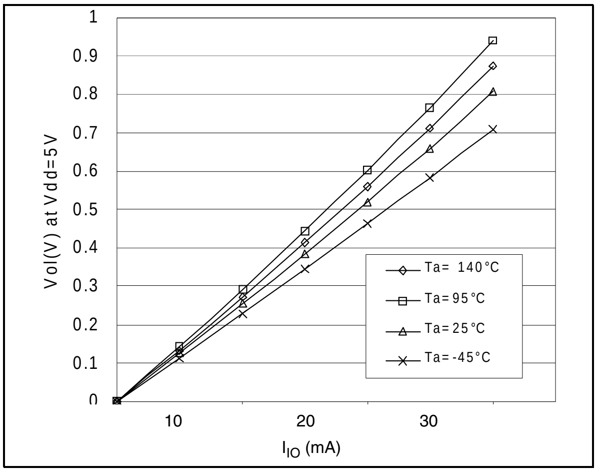


Figure 72. Typ. V_{OL} at V_{DD}=5V (high-sink ports)



Notes:

1. The I_{IO} current sunk must always respect the absolute maximum rating specified in Section 12.2.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS}.

2. The I_{IO} current sourced must always respect the absolute maximum rating specified in Section 12.2.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VDD}. True open drain I/O pins do not have V_{OH}.

13.2 THERMAL CHARACTERISTICS

Symbol	Ratings	Value	Unit
R_{thJA}	Package thermal resistance (junction to ambient) TQFP44 10x10 TQFP32 7x7 SDIP42 600mil SDIP32 200mil	 52 70 55 50	°C/W
P_D	Power dissipation [1)]	500	mW
T_{Jmax}	Maximum junction temperature [2)]	150	°C

Notes:

1. The power dissipation is obtained from the formula $P_D=P_{INT}+P_{PORT}$ where P_{INT} is the chip internal power ($I_{DD}xV_{DD}$) and P_{PORT} is the port power dissipation determined by the user.
2. The average chip-junction temperature can be obtained from the formula $T_J = T_A + P_D$ x RthJA.

16 IMPORTANT NOTES ON ST72F324B FLASH DEVICES:

With the objective of continuous improvement, ST has developed new ST72F324B devices. These devices are fully compatible with all ROM features and provide an improved price/performance ratio compared to the ST72F324 flash devices.

A summary of the technical improvements is given below.

Refer to separate ST72324B datasheet for the ordering information and full specifications.

16.1 Reset Pin Logic levels

In ST72F324B Flash devices, the V_{IH}/V_{IL} levels for the reset pin are the same as specified for ROM devices

16.2 Wake-Up from Active Halt mode using external interrupts

In ST72F324B Flash devices, any external interrupt that capable of waking-up the MCU from Halt mode can also wake-up the MCU from Active Halt mode. Consequently note 1 below Table 8 on page 36 does not apply to 'B' devices.

16.3 PLL Jitter

In ST72F324B Flash devices, PLL clock accuracy is improved and the jitter is the same as specified for ROM devices

16.4 Active Halt Power Consumption

In ST72F324B Flash devices, the power consumption in Active Halt mode is specified as 230µA max. See Table 12.5.1 on page 120 for test conditions.

16.5 Timer A Registers

In ST72F324B Flash devices, all Timer A registers are present and their functionality is the same as described for ROM devices in the ST72324B datasheet.